

## High speed Driver with bootstrapping for dual Power MOSFETs



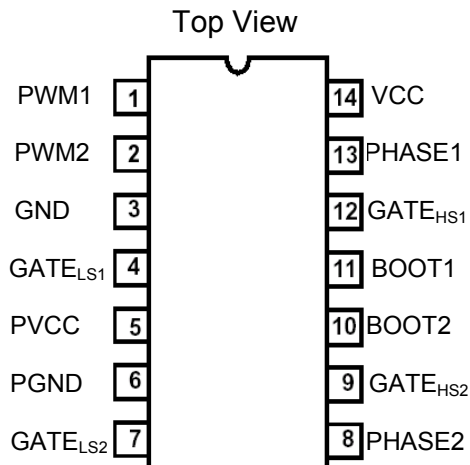
P-DSO-14-3

### Features

- Fast rise and fall times for frequencies up to 2 MHz
- Capable of sinking more than 4 A peak current for lowest switching losses
- Charges the High Side and Low Side MOSFET's gate to 6..12 V according to PVCC setting.
- Adjustable High Side and Low Side MOSFET gate drive voltage via PVCC pin for optimizing ON losses and gate drive losses
- Integrates the bootstrap diode for reducing the part count
- Prevents from cross-conducting by adaptive gate drive control
- High voltage rating on Phase node
- Supports shut-down mode for very low quiescent current through three-state input
- Compatible to standard PWM controller ICs (Intersil, Analog Devices)
- Floating High Side MOSFET drive
  - Ideal for multi-phase Desktop CPU supplies on motherboards and VRM's

Type	Package	Marking	Ordering Code
TDA21102	P-DSO-14-3	21102	Q67042-S4244

### Pinout



Number	Name	Description
1	PWM1	Input for the PWM1 controller signal
2	PWM2	Input for the PWM2 controller signal
3	GND	Ground
4	GATE <sub>LS1</sub>	Gate drive output for the N-Channel Low Side MOSFET 1.
5	PVCC	Input to adjust the High Side gate drive
6	PGND	Power ground return for the Low Side Drivers
7	GATE <sub>LS2</sub>	Gate drive output for the N-Channel Low Side MOSFET 2.
8	PHASE2	To be connected to the junction of the High Side and the Low Side MOSFET 2
9	GATE <sub>HS2</sub>	Gate drive output for the N-Channel High Side MOSFET 2.
10	BOOT2	Floating bootstrap pin. To be connected to the external bootstrap capacitor to generate the gate drive voltage for the High Side N-Channel MOSFET 2.
11	BOOT1	Floating bootstrap pin. To be connected to the external bootstrap capacitor to generate the gate drive voltage for the High Side N-Channel MOSFET 1.
12	GATE <sub>HS1</sub>	Gate drive output for the N-Channel High Side MOSFET 1.
13	PHASE1	To be connected to the junction of the High Side and the Low Side MOSFET 1
14	VCC	Supply Voltage

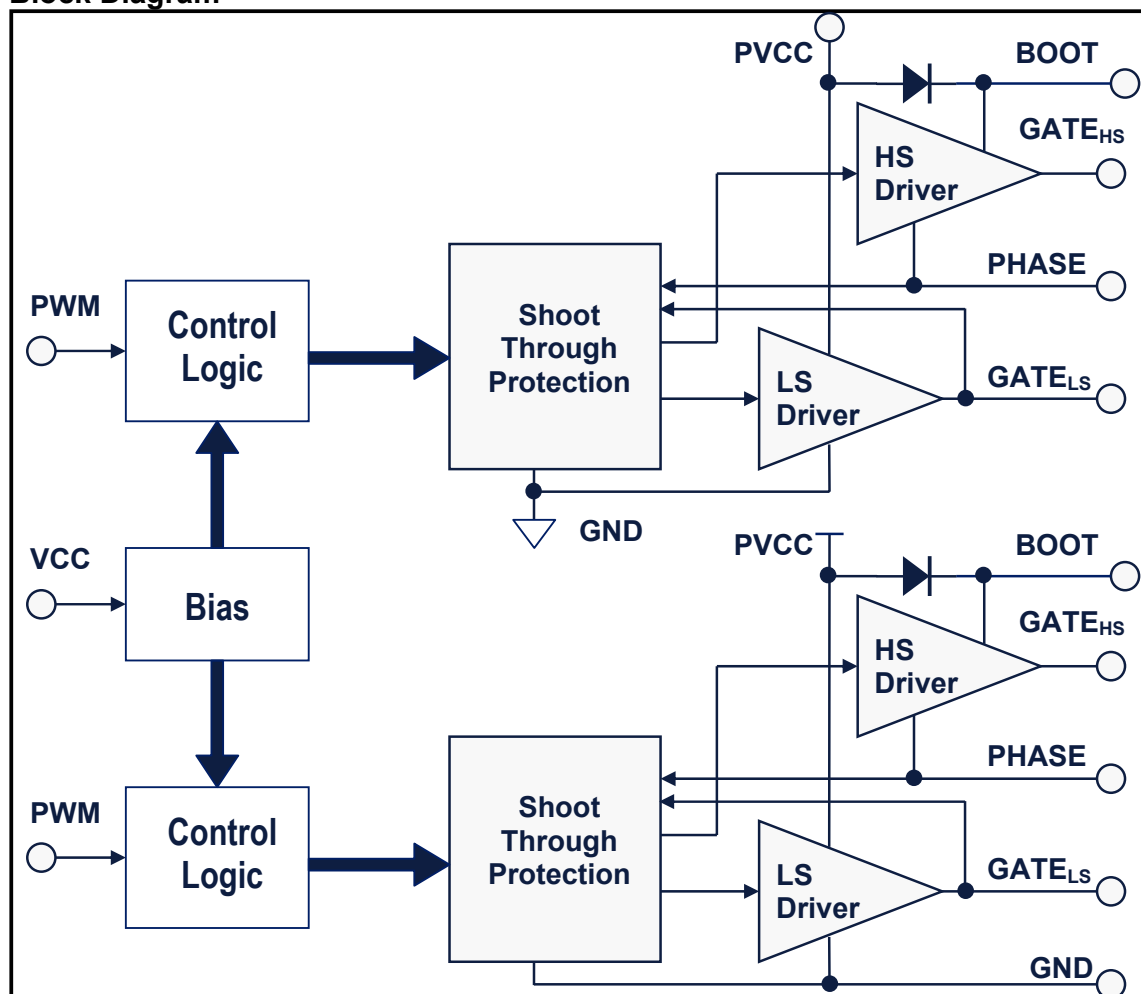
## General Description

The dual high speed driver is designed to drive a wide range of N-Channel low side and N-Channel high side MOSFETs with varying gate charges. It has a small propagation delay from input to output, short rise and fall times and the same pin configuration as the HIP6602B. In addition it provides several protection features as well as a shut down mode for efficiency reasons. The high breakdown voltage makes it suitable for mobile applications.

## Target application

The dual high speed driver is designed to work well in half-bridge type circuits where dual N-Channel MOSFETs are utilized. A circuit designer can fully take advantage of the driver's capabilities in high-efficiency, high-density synchronous DC/DC converters that operate at high switching frequencies, e.g. in multi-phase converters for CPU supplies on motherboards and VRM's but also in motor drive and class-D amplifier type applications.

## Block Diagram



**Absolute Maximum Ratings**

 At  $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

Parameter	Symbol	Value		Unit
		Min.	Max.	
Voltage supplied to 'VCC' pin	$V_{VCC}$	-0.3	25	V
Voltage supplied to 'PVCC' pin	$V_{PVCC}$	-0.3	25	
Voltage supplied to 'PWM' pin	$V_{PWM}$	-0.3	5.5	
Voltage supplied to 'BOOT' pin referenced to 'PHASE'	$V_{BOOT} - V_{PHASE}$	-0.3	25	
Voltage rating at 'PHASE' pin, DC	$V_{PHASE}$	-1	25	
Voltage rating at 'PHASE' pin, $t_{pulse\_max} = 500\text{ns}$ Max Duty Cycle = 2%		-20	30	
Junction temperature	$T_J$	-25	150	$^{\circ}\text{C}$
Storage temperature	$T_S$	-55	150	
ESD Rating; Human Body Model			4	kV
IEC climatic category; DIN EN 60068-1			55/150/56	-

**Thermal Characteristic**

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction-case	Rth-JC		44,7		K/W
Thermal resistance, junction-ambient	Rth-JA		116,2		

**Electrical Characteristic**

 At  $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

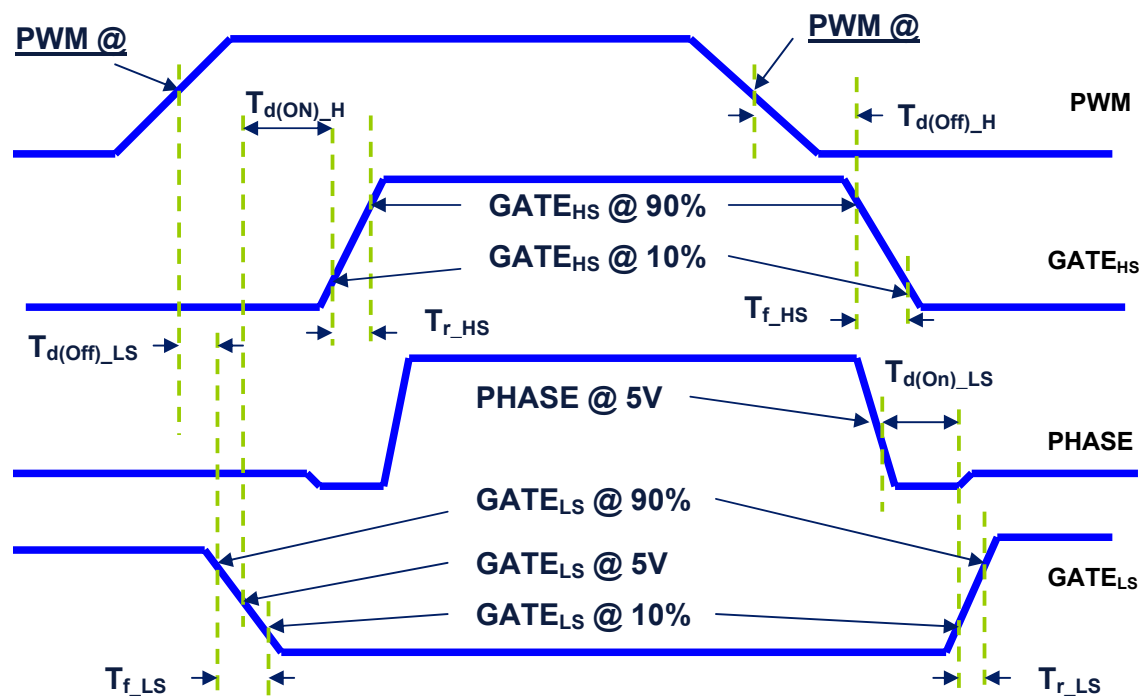
Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Supply Characteristic						
Bias supply current	I <sub>VCC</sub>	f = 1 MHz, NO LOAD V <sub>PVCC</sub> = V <sub>VCC</sub> = 12 V		0.95	1.65	mA
Quiescent current	I <sub>VCCQ</sub>	1.8 V ≤ V <sub>PWM</sub> ≤ 3.0 V		0.75	3	
Power supply current	I <sub>PVCC</sub>	f = 1 MHz, NO LOAD V <sub>PVCC</sub> = V <sub>VCC</sub> = 12 V		26		
Under-voltage lockout		V <sub>VCC</sub> rising threshold	9.7	10.1	10.5	V
Under-voltage lockout		V <sub>VCC</sub> falling threshold	7.3	7.6	8.0	V
Input Characteristic						
Current in 'PWM' pin	I <sub>PWM L</sub>	V <sub>PWM</sub> = 0.4 V	-80	115	-150	μA
Current in 'PWM' pin	I <sub>PWM H</sub>	V <sub>PWM</sub> = 4.5 V	120	180	250	
Shut down window	V <sub>IN_SHUT</sub>	t <sub>SHUT</sub> > 320 ns	1.7		3.1	V
Shut down hold-off time	t <sub>SHUT</sub>	1.7 V ≤ V <sub>PWM</sub> ≤ 3.1 V	100	230	350	ns
PWM pin open	V <sub>PWM O</sub>		1.8	2.0	2.2	

PWM Low level threshold (falling)	$V_{PWM\_L}$		1.45	1.55		V
PWM High level threshold (rising)	$V_{PWM\_H}$			3.45	3.6	
Pulse Width High Side	$t_p$	= Pulse with on PWM pin	40			ns

At  $T_j = 25\text{ }^{\circ}\text{C}$ , unless otherwise specified

<b>Dynamic Characteristic</b>						
Turn-on propagation Delay High Side*	$t_{d(ON)\_HS}$	$P_{PVCC} = V_{VCC} = 12\text{ V}$ $C_{ISS} = 3000\text{ pF}$		27	35	ns
Turn-off propagation delay High Side	$t_{d(OFF)\_HS}$			16	21	
Rise time High Side	$t_{r\_HS}$			20	25	
Fall time High Side	$t_{f\_HS}$			11	20	
Turn-on propagation Delay Low Side	$t_{d(ON)\_LS}$			20	23	
Turn-off propagation delay Low Side	$t_{d(OFF)\_LS}$			13	20	
Rise time Low Side	$t_{r\_LS}$			22	25	
Fall time Low Side	$t_{f\_LS}$			13	20	

### Measurement Timing diagram



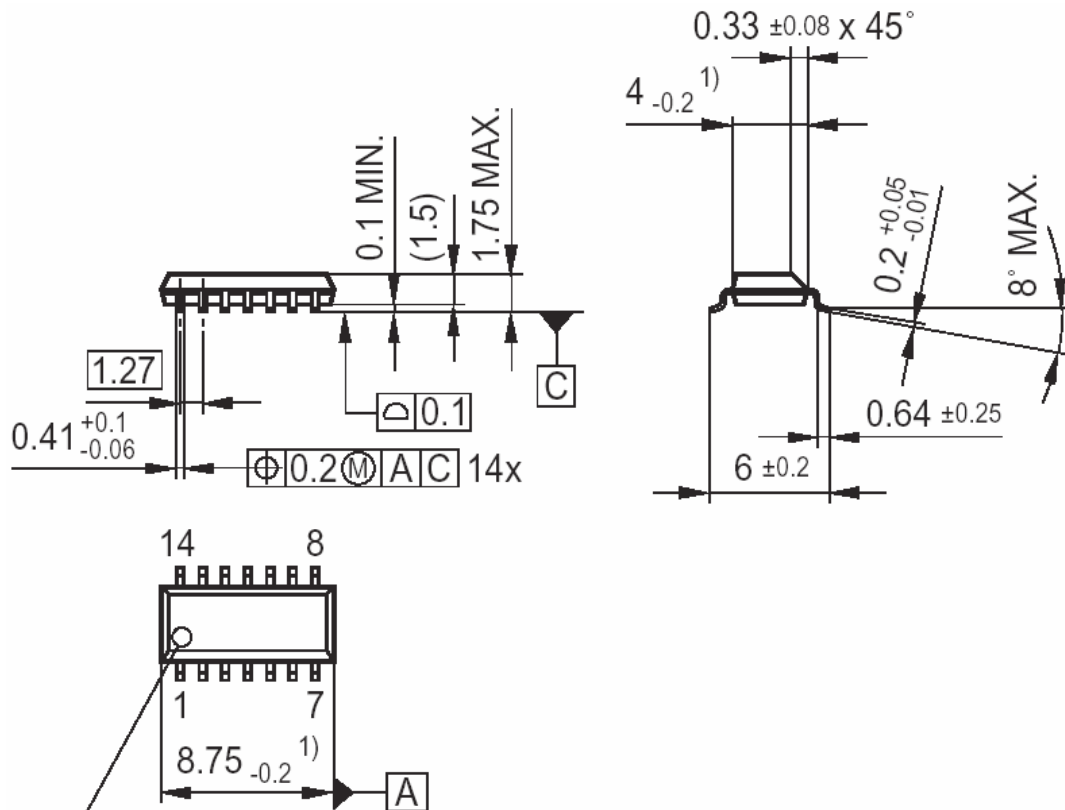
**Operating Conditions**

 At  $T_J = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Voltage supplied to 'VCC' pin	$V_{VCC}$		10.8		13.2	V
Voltage supplied to 'PVCC' pin	$V_{PVCC}$		6		13.2	V
Input signal transition frequency	f		0.1		2	MHz
Power dissipation	$P_{TOT}$	$T_A = 25\text{ °C}, T_J = 125\text{ °C}$		0.9		W
Junction temperature	$T_J$		-25		150	°C

 At  $T_J = 25\text{ °C}$ , unless otherwise specified

Parameter		Conditions	Values			Unit
			Min.	Typ.	Max.	
Output Characteristic High Side (HS) and Low Side (LS), ensured by design						
Output Resistance	HS; Source	$P_{PVCC} = V_{VCC} = 12\text{ V}$ $I_{HS\_SRC} = 2\text{ A}$		1.2		$\Omega$
	HS; Sink	$P_{PVCC} = V_{VCC} = 12\text{ V}$		1	1.5	$\Omega$
	LS; Source	$P_{PVCC} = V_{VCC} = 12\text{ V}$ $I_{HS\_SRC} = 2\text{ A}$		1		$\Omega$
	LS; Sink	$P_{PVCC} = V_{VCC} = 12\text{ V}$		1	1.3	$\Omega$
Peak output-current	HS; Source	$P_{PVCC} = V_{VCC} = 12\text{ V}$	4			A
	HS; Sink	$t_{P\_HS} / \text{Pulse} < 20\text{ ns}$	4			
	LS; Source	$t_{P\_LS} / \text{Pulse} < 40\text{ ns}$	4			
	LS; Sink	$D_{HS} < 2\%, D_{LS} < 4\%$	4			

**Package Drawing P-DSO-14-3**


Index Marking

<sup>1)</sup> Does not include plastic or metal protrusion of 0.15 max. per side

**Layout Footprints**


e	A	L	B
1,27 mm	5,69 mm	1,31 mm	0,65 mm

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